

# High-Speed, Single-Supply, Rail-to-Rail OPERATIONAL AMPLIFIERS

## *MicroAmplifier™* Series

### FEATURES

- RAIL-TO-RAIL INPUT
- RAIL-TO-RAIL OUTPUT (within 10mV)
- WIDE BANDWIDTH: 38MHz
- HIGH SLEW RATE: 22V/ $\mu$ s
- LOW NOISE: 5nV/ $\sqrt{\text{Hz}}$
- LOW THD+NOISE: 0.0006%
- UNITY-GAIN STABLE
- *Micro*SIZE PACKAGES
- SINGLE, DUAL, AND QUAD

### APPLICATIONS

- CELL PHONE PA CONTROL LOOPS
- DRIVING A/D CONVERTERS
- VIDEO PROCESSING
- DATA ACQUISITION
- PROCESS CONTROL
- AUDIO PROCESSING
- COMMUNICATIONS
- ACTIVE FILTERS
- TEST EQUIPMENT

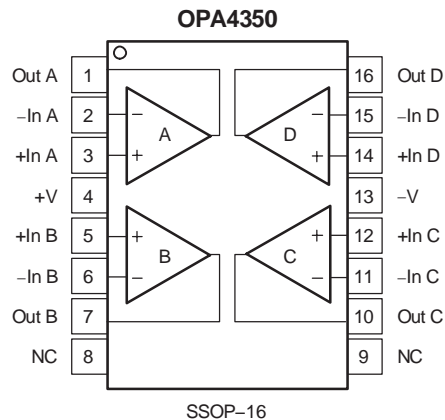
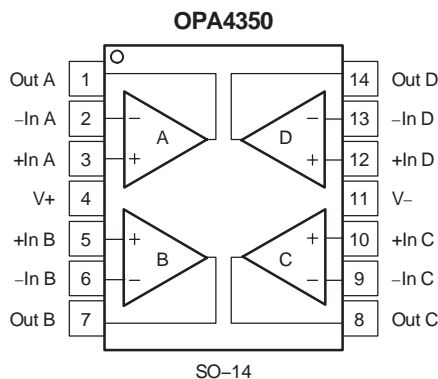
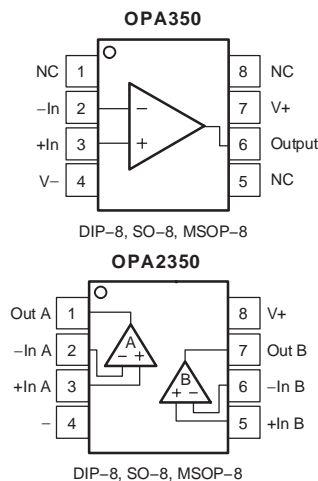
### DESCRIPTION

The OPA350 series rail-to-rail CMOS operational amplifiers are optimized for low voltage, single-supply operation. Rail-to-rail input/output, low noise (5nV/ $\sqrt{\text{Hz}}$ ), and high speed operation (38MHz, 22V/ $\mu$ s) make them ideal for driving sampling Analog-to-Digital (A/D) converters. They are also well suited for cell phone PA control loops and video processing (75 $\Omega$  drive capability) as well as audio and general purpose applications. Single, dual, and quad versions have identical specifications for maximum design flexibility.

The OPA350 series operates on a single supply as low as 2.5V with an input common-mode voltage range that extends 300mV below ground and 300mV above the positive supply. Output voltage swing is to within 10mV of the supply rails with a 10k $\Omega$  load. Dual and quad designs feature completely independent circuitry for lowest crosstalk and freedom from interaction.

The single (OPA350) and dual (OPA2350) come in the miniature MSOP-8 surface mount, SO-8 surface mount, and DIP-8 packages. The quad (OPA4350) packages are the space-saving SSOP-16 surface mount and SO-14 surface mount. All are specified from -40°C to +85°C and operate from -55°C to +150°C.

SPICE model available at [www.ti.com](http://www.ti.com)



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

All trademarks are the property of their respective owners.

## ABSOLUTE MAXIMUM RATINGS<sup>(1)</sup>

Supply Voltage .....	7.0V
Signal Input Terminals <sup>(2)</sup> , Voltage .....	(V <sub>-</sub> ) – 0.3V to (V <sub>+</sub> ) + 0.3V
Current .....	10mA
Open Short-Circuit Current <sup>(3)</sup> .....	Continuous
Operating Temperature Range .....	–55°C to +150°C
Storage Temperature Range .....	–55°C to +150°C
Junction Temperature .....	+150°C
Lead Temperature (soldering, 10s) .....	+300°C

(1) Stresses above these ratings may cause permanent damage.

Exposure to absolute maximum conditions for extended periods may degrade device reliability. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those specified is not implied.

(2) Input terminals are diode-clamped to the power-supply rails.

Input signals that can swing more than 0.3V beyond the supply rails should be current limited to 10mA or less.

(3) Short-circuit to ground, one amplifier per package.

## ELECTROSTATIC DISCHARGE SENSITIVITY



This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

## PACKAGE/ORDERING INFORMATION<sup>(1)</sup>

PRODUCT	PACKAGE-LEAD	PACKAGE DESIGNATOR	SPECIFIED TEMPERATURE RANGE	PACKAGE MARKING	ORDERING NUMBER	TRANSPORT MEDIA, QUANTITY
<b>SINGLE</b>						
OPA350EA	MSOP-8	DGK	–40°C to +85°C	C50	OPA350EA/250	Tape and Reel, 250
					OPA350EA/2K5	Tape and Reel, 2500
OPA350UA	SO-8	D	–40°C to +85°C	OPA350UA	OPA350UA	Rails
					OPA350UA/2K5	Tape and Reel, 2500
OPA350PA	DIP-8	P	–40°C to +85°C	OPA350PA	OPA350PA	Rails
<b>DUAL</b>						
OPA2350EA	MSOP-8	DGK	–40°C to +85°C	D50	OPA2350EA/250	Tape and Reel, 250
					OPA2350EA/2K5	Tape and Reel, 2500
OPA2350UA	SO-8	D	–40°C to +85°C	OPA2350UA	OPA2350UA	Rails
					OPA2350UA/2K5	Tape and Reel, 2500
OPA2350PA	DIP-8	P	–40°C to +85°C	OPA2350PA	OPA2350PA	Rails
<b>QUAD</b>						
OPA4350EA	SSOP-16	DBQ	–40°C to +85°C	OPA4350EA	OPA4350EA/250	Tape and Reel, 250
					OPA4350EA/2K5	Tape and Reel, 2500
OPA4350UA	SO-14	D	–40°C to +85°C	OPA4350UA	OPA4350UA	Rails
					OPA4350UA/2K5	Tape and Reel, 2500

(1) For the most current package and ordering information, see the Package Option Addendum located at the end of this data sheet.

## ELECTRICAL CHARACTERISTICS: $V_S = 2.7V$ to $5.5V$

**Boldface** limits apply over the temperature range,  $T_A = -40^\circ C$  to  $+85^\circ C$ .  $V_S = 5V$ .

All specifications at  $T_A = +25^\circ C$ ,  $R_L = 1k\Omega$  connected to  $V_S/2$  and  $V_{OUT} = V_S/2$ , unless otherwise noted.

PARAMETER		TEST CONDITIONS	OPA350, OPA2350, OPA4350			UNIT
			MIN	TYP(1)	MAX	
OFFSET VOLTAGE						
Input Offset Voltage	V <sub>OS</sub>	V <sub>S</sub> = 5V		±150	±500	μV
T <sub>A</sub> = −40°C to +85°C					±1	mV
vs Temperature		T <sub>A</sub> = −40°C to +85°C		±4		μV/°C
vs Power-Supply Rejection Ratio	PSRR	V <sub>S</sub> = 2.7V to 5.5V, V <sub>CM</sub> = 0V		40	150	μV/V
T <sub>A</sub> = −40°C to +85°C		V <sub>S</sub> = 2.7V to 5.5V, V <sub>CM</sub> = 0V			175	μV/V
Channel Separation (dual, quad)		dc		0.15		μV/V
INPUT BIAS CURRENT						
Input Bias Current	I <sub>B</sub>			±0.5	±10	pA
vs Temperature			See Typical Characteristics			
Input Offset Current	I <sub>OS</sub>			±0.5	±10	pA
NOISE						
Input Voltage Noise, f = 100Hz to 400kHz				4		μVrms
Input Voltage Noise Density, f = 10kHz	e <sub>n</sub>			7		nV/√Hz
Input Current Noise Density, f = 100kHz				5		nV/√Hz
Current Noise Density, f = 10kHz	i <sub>n</sub>			4		fA/√Hz
INPUT VOLTAGE RANGE						
Common-Mode Voltage Range	V <sub>CM</sub>	T <sub>A</sub> = −40°C to +85°C	−0.1		(V+) + 0.1	V
Common-Mode Rejection Ratio	CMRR	V <sub>S</sub> = 2.7V, −0.1V < V <sub>CM</sub> < 2.8V	66	84		dB
		V <sub>S</sub> = 5.5V, −0.1V < V <sub>CM</sub> < 5.6V	74	90		dB
T <sub>A</sub> = −40°C to +85°C		V <sub>S</sub> = 5.5V, −0.1V < V <sub>CM</sub> < 5.6V	74			dB
INPUT IMPEDANCE						
Differential				10 <sup>13</sup>    2.5		Ω    pF
Common-Mode				10 <sup>13</sup>    6.5		Ω    pF
OPEN-LOOP GAIN						
Open-Loop Voltage Gain	A <sub>OL</sub>	R <sub>L</sub> = 10kΩ, 50mV < V <sub>O</sub> < (V+) − 50mV	100	122		dB
T <sub>A</sub> = −40°C to +85°C		R <sub>L</sub> = 10kΩ, 50mV < V <sub>O</sub> < (V+) − 50mV	100			dB
		R <sub>L</sub> = 1kΩ, 200mV < V <sub>O</sub> < (V+) − 200mV	100	120		dB
T <sub>A</sub> = −40°C to +85°C		R <sub>L</sub> = 1kΩ, 200mV < V <sub>O</sub> < (V+) − 200mV	100			dB
FREQUENCY RESPONSE						
		C <sub>L</sub> = 100pF				
Gain-Bandwidth Product	GBW	G = 1		38		MHz
Slew Rate	SR	G = 1		22		V/μs
Settling Time: 0.1%		G = ±1, 2V Step		0.22		μs
0.01%		G = ±1, 2V Step		0.5		μs
Overload Recovery Time		V <sub>IN</sub> • G = V <sub>S</sub>		0.1		μs
Total Harmonic Distortion + Noise	THD+N	R <sub>L</sub> = 600Ω, V <sub>O</sub> = 2.5V <sub>PP</sub> (2), G = 1, f = 1kHz		0.0006		%
Differential Gain Error		G = 2, R <sub>L</sub> = 600Ω, V <sub>O</sub> = 1.4V(3)		0.17		%
Differential Phase Error		G = 2, R <sub>L</sub> = 600Ω, V <sub>O</sub> = 1.4V(3)		0.17		deg

(1)  $V_S = +5V$ .

(2)  $V_{OUT} = 0.25V$  to  $2.75V$ .

(3) NTSC signal generator used. See Figure 6 for test circuit.

(4) Output voltage swings are measured between the output and power supply rails.

(5) See typical characteristic curve, *Output Voltage Swing vs Output Current*.

# **ELECTRICAL CHARACTERISTICS: $V_S = 2.7V$ to $5.5V$ (continued)**

**Boldface** limits apply over the temperature range,  $T_A = -40^{\circ}C$  to  $+85^{\circ}C$ .  $V_S = 5V$ .

All specifications at  $T_A = +25^{\circ}C$ ,  $R_L = 1k\Omega$  connected to  $V_S/2$  and  $V_{OUT} = V_S/2$ , unless otherwise noted.

PARAMETER		TEST CONDITIONS	OPA350, OPA2350, OPA4350			UNIT
			MIN	TYP(1)	MAX	
<b>OUTPUT</b>						
Voltage Output Swing from Rail(4)	V <sub>OUT</sub>	R <sub>L</sub> = 10kΩ, A <sub>OL</sub> ≥ 100dB		10	50	mV
T <sub>A</sub> = −40°C to +85°C		R <sub>L</sub> = 10kΩ, A <sub>OL</sub> ≥ 100dB			50	mV
		R <sub>L</sub> = 1kΩ, A <sub>OL</sub> ≥ 100dB		25	200	mV
T <sub>A</sub> = −40°C to +85°C		R <sub>L</sub> = 1kΩ, A <sub>OL</sub> ≥ 100dB			200	mV
Output Current	I <sub>OUT</sub>			±40(5)		mA
Short-Circuit Current	I <sub>SC</sub>			±80		mA
Capacitive Load Drive	C <sub>LOAD</sub>		See Typical Characteristics			
<b>POWER SUPPLY</b>						
Operating Voltage Range	V <sub>S</sub>	T <sub>A</sub> = −40°C to +85°C	2.7		5.5	V
Minimum Operating Voltage				2.5		V
Quiescent Current (per amplifier)	I <sub>Q</sub>	I <sub>O</sub> = 0		5.2	7.5	mA
T <sub>A</sub> = −40°C to +85°C		I <sub>O</sub> = 0			8.5	mA
<b>TEMPERATURE RANGE</b>						
Specified Range			−40		+85	°C
Operating Range			−55		+150	°C
Storage Range			−55		+150	°C
Thermal Resistance	θ <sub>JA</sub>					
MSOP-8 Surface Mount				150		°C/W
SO-8 Surface Mount				150		°C/W
DIP-8				100		°C/W
SO-14 Surface Mount				100		°C/W
SSOP-16 Surface Mount				100		°C/W

(1)  $V_S = +5V$ .

(2)  $V_{OUT} = 0.25V$  to  $2.75V$ .

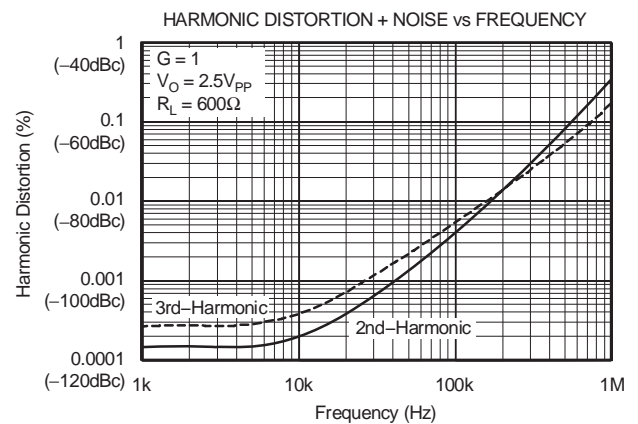
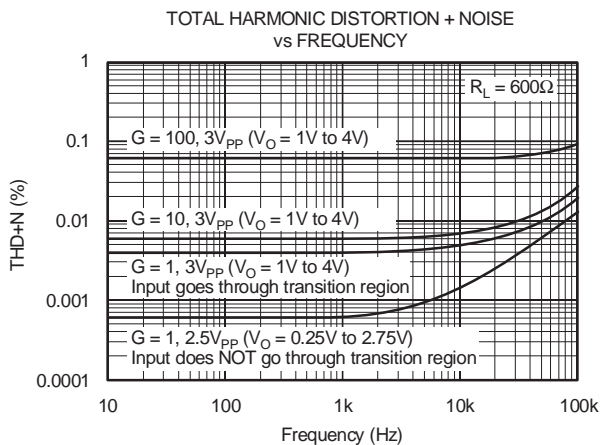
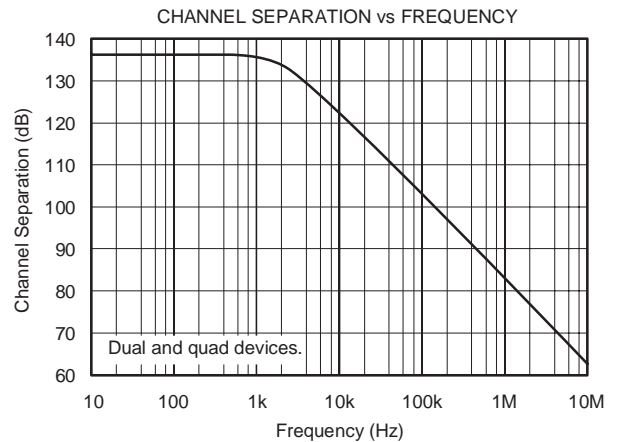
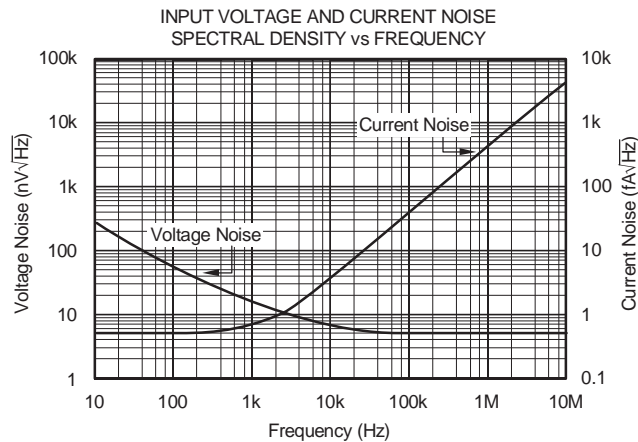
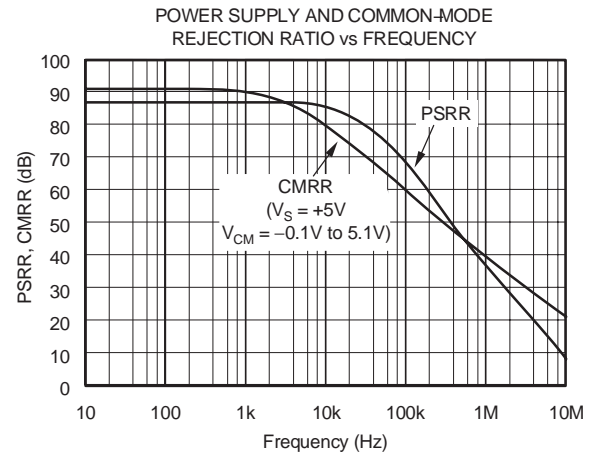
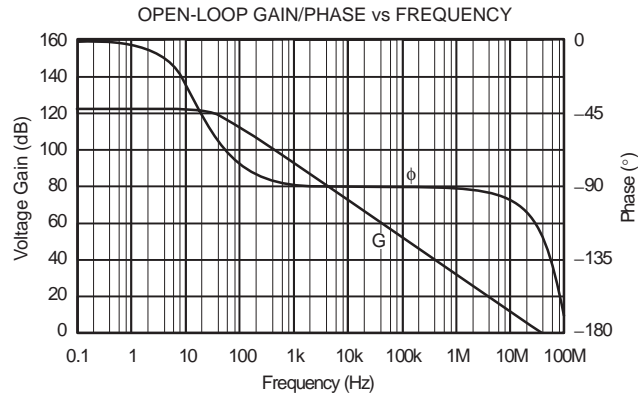
(3) NTSC signal generator used. See Figure 6 for test circuit.

(4) Output voltage swings are measured between the output and power supply rails.

(5) See typical characteristic curve, *Output Voltage Swing vs Output Current*.

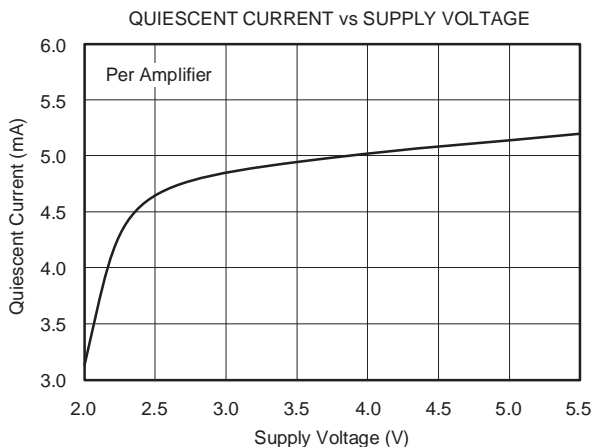
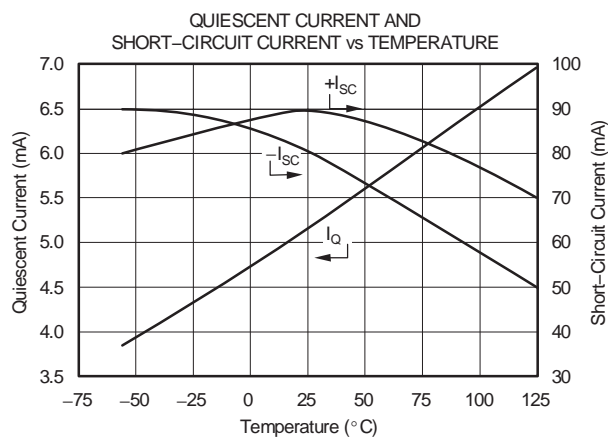
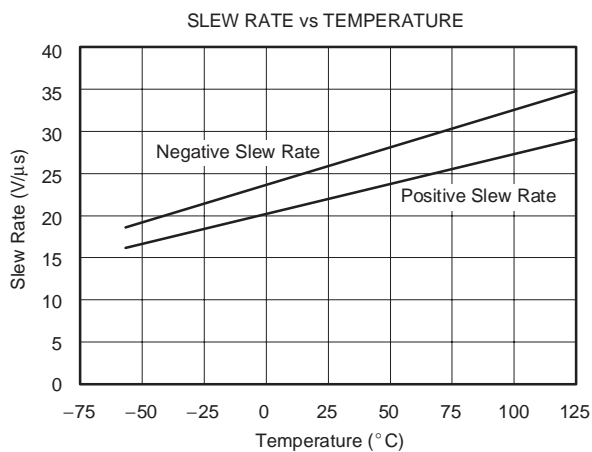
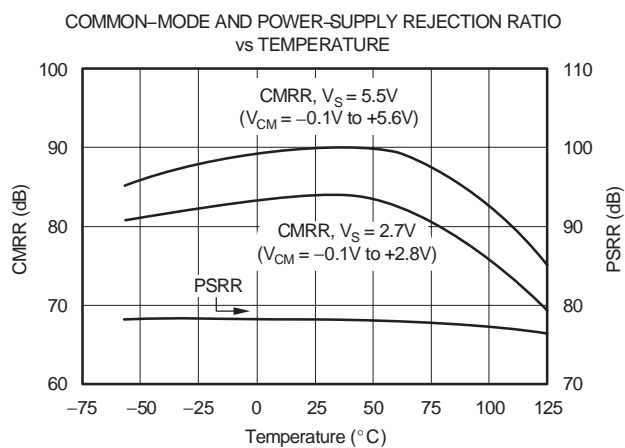
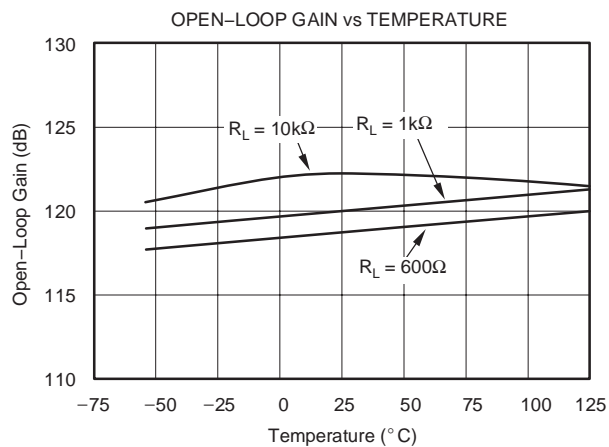
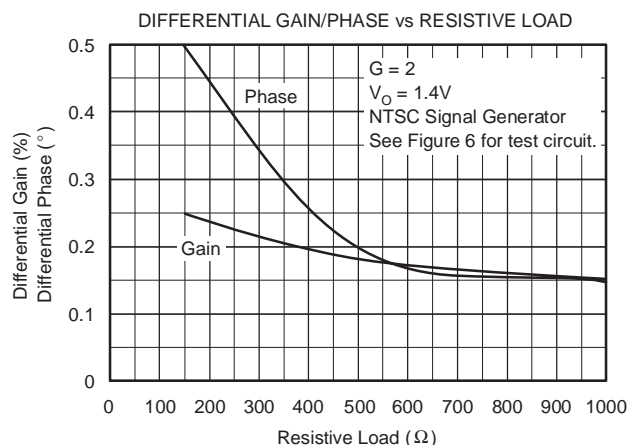
## TYPICAL CHARACTERISTICS

All specifications at  $T_A = +25^\circ\text{C}$ ,  $V_S = +5\text{V}$ , and  $R_L = 1\text{k}\Omega$  connected to  $V_S/2$ , unless otherwise noted.



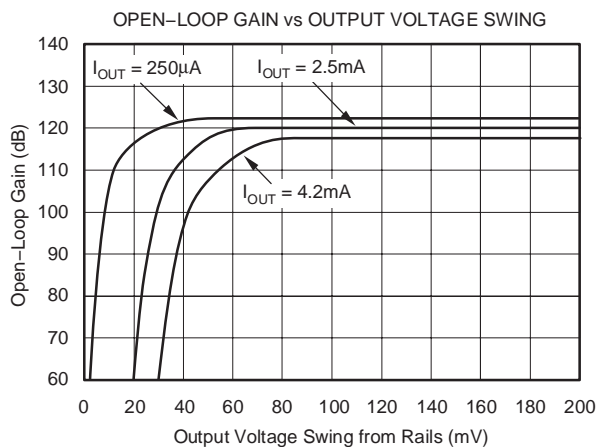
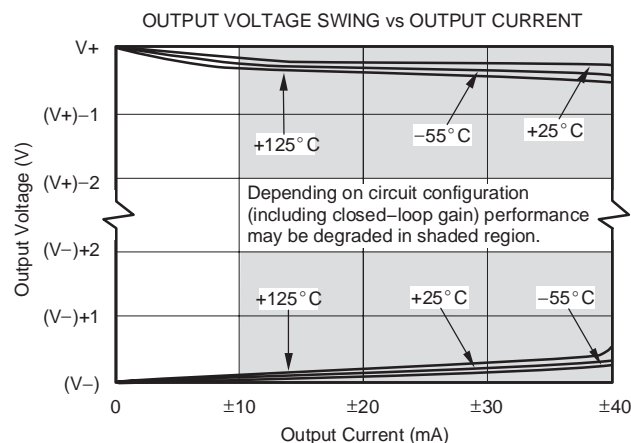
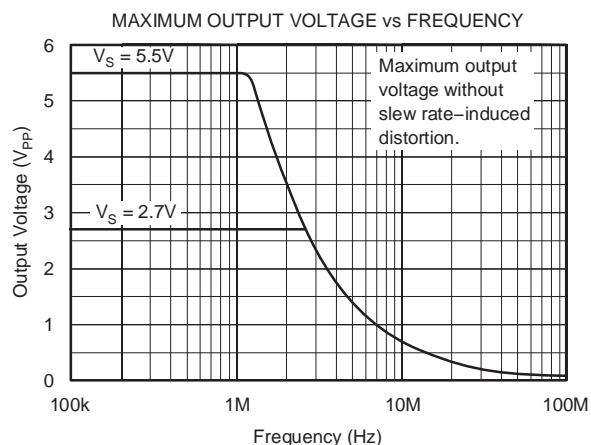
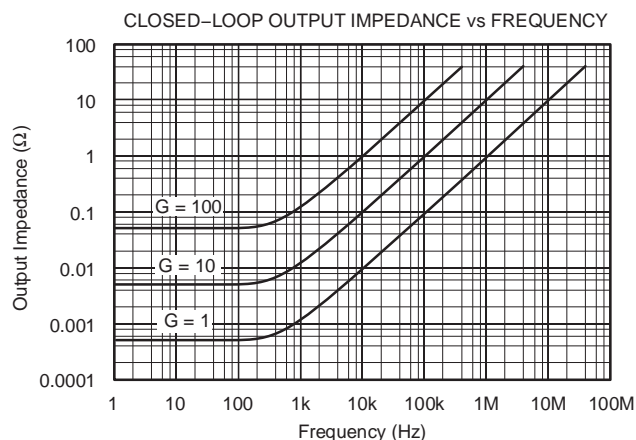
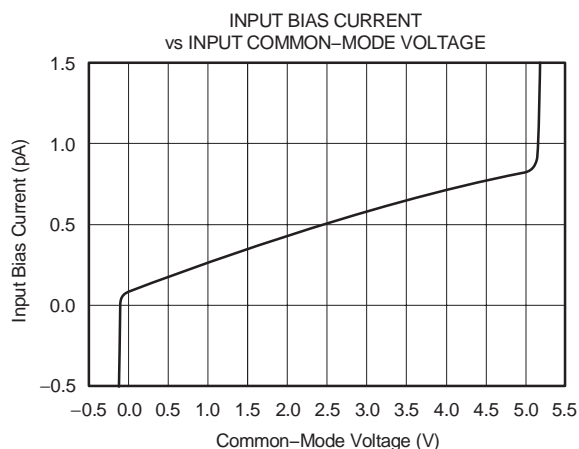
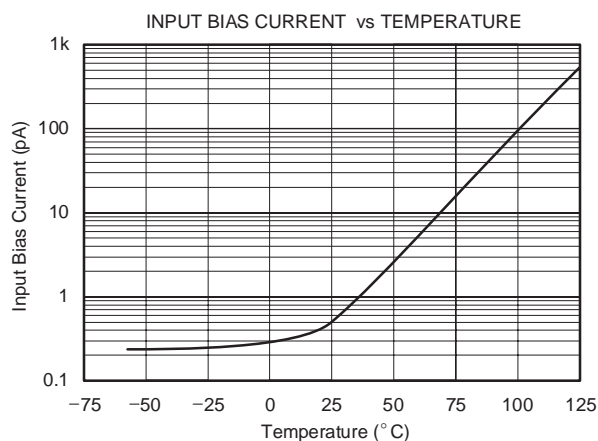
## TYPICAL CHARACTERISTICS (continued)

All specifications at  $T_A = +25^\circ\text{C}$ ,  $V_S = +5\text{V}$ , and  $R_L = 1\text{k}\Omega$  connected to  $V_S/2$ , unless otherwise noted.



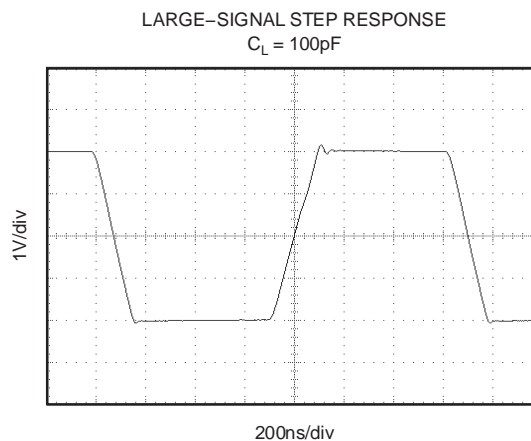
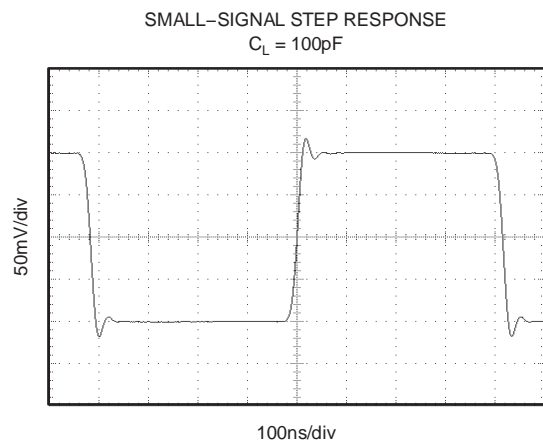
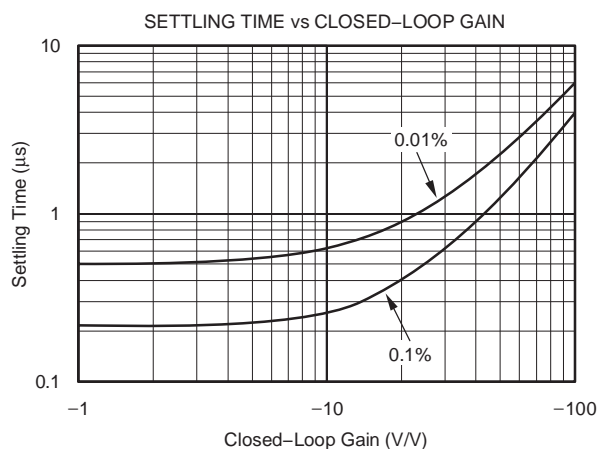
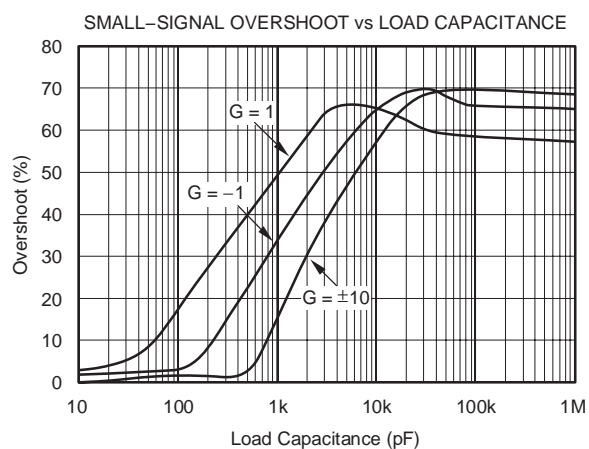
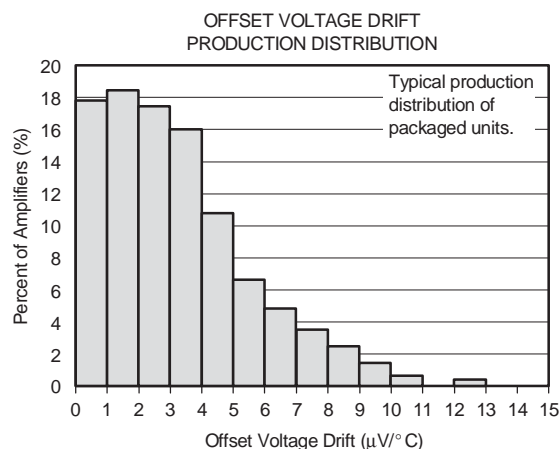
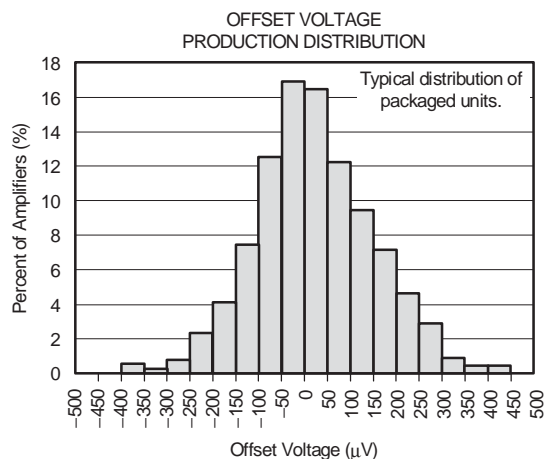
## TYPICAL CHARACTERISTICS (continued)

All specifications at  $T_A = +25^\circ\text{C}$ ,  $V_S = +5\text{V}$ , and  $R_L = 1\text{k}\Omega$  connected to  $V_S/2$ , unless otherwise noted.



## TYPICAL CHARACTERISTICS (continued)

All specifications at  $T_A = +25^\circ\text{C}$ ,  $V_S = +5\text{V}$ , and  $R_L = 1\text{k}\Omega$  connected to  $V_S/2$ , unless otherwise noted.





## APPLICATIONS INFORMATION

OPA350 series op amps are fabricated on a state-of-the-art 0.6 micron CMOS process. They are unity-gain stable and suitable for a wide range of general-purpose applications. Rail-to-rail input/output make them ideal for driving sampling A/D converters. They are also well-suited for controlling the output power in cell phones. These applications often require high speed and low noise. In addition, the OPA350 series offers a low-cost solution for general-purpose and consumer video applications (75Ω drive capability).

Excellent ac performance makes the OPA350 series well-suited for audio applications. Their bandwidth, slew rate, low noise ( $5\text{nV}/\sqrt{\text{Hz}}$ ), low THD (0.0006%), and small package options are ideal for these applications. The class AB output stage is capable of driving 600Ω loads connected to any point between  $V_+$  and ground.

Rail-to-rail input and output swing significantly increases dynamic range, especially in low voltage supply applications. Figure 1 shows the input and output waveforms for the OPA350 in unity-gain configuration. Operation is from a single +5V supply with a 1kΩ load connected to  $V_S/2$ . The input is a 5V<sub>PP</sub> sinusoid. Output voltage swing is approximately 4.95V<sub>PP</sub>.

Power supply pins should be bypassed with 0.01μF ceramic capacitors.

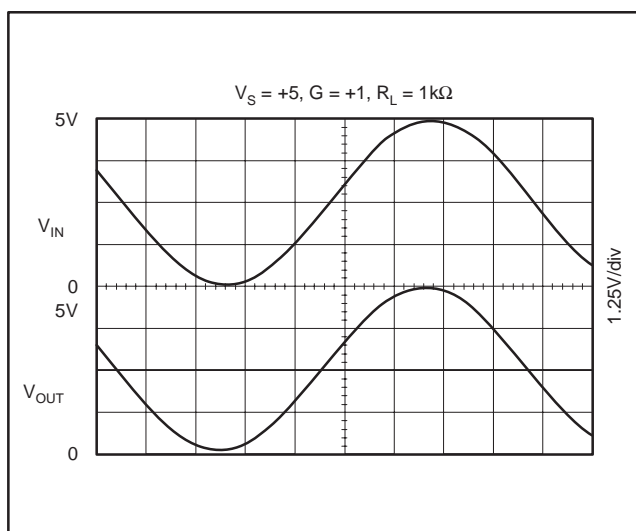


Figure 1. Rail-to-Rail Input and Output

## OPERATING VOLTAGE

OPA350 series op amps are fully specified from +2.7V to +5.5V. However, supply voltage may range from +2.5V to +5.5V. Parameters are tested over the specified supply range—a unique feature of the OPA350 series. In addition, many specifications apply from  $-40^{\circ}\text{C}$  to  $+85^{\circ}\text{C}$ . Most behavior remains virtually unchanged throughout the full operating voltage range. Parameters that vary significantly with operating voltage or temperature are shown in the typical characteristics.

## RAIL-TO-RAIL INPUT

The tested input common-mode voltage range of the OPA350 series extends 100mV beyond the supply rails. This is achieved with a complementary input stage—an N-channel input differential pair in parallel with a P-channel differential pair, as shown in Figure 2. The N-channel pair is active for input voltages close to the positive rail, typically  $(V_+) - 1.8\text{V}$  to 100mV above the positive supply, while the P-channel pair is on for inputs from 100mV below the negative supply to approximately  $(V_+) - 1.8\text{V}$ . There is a small transition region, typically  $(V_+) - 2\text{V}$  to  $(V_+) - 1.6\text{V}$ , in which both pairs are on. This 400mV transition region can vary  $\pm 400\text{mV}$  with process variation. Thus, the transition region (both input stages on) can range from  $(V_+) - 2.4\text{V}$  to  $(V_+) - 2.0\text{V}$  on the low end, up to  $(V_+) - 1.6\text{V}$  to  $(V_+) - 1.2\text{V}$  on the high end.

OPA350 series op amps are laser-trimmed to reduce offset voltage difference between the N-channel and P-channel input stages, resulting in improved common-mode rejection and a smooth transition between the N-channel pair and the P-channel pair. However, within the 400mV transition region PSRR, CMRR, offset voltage, offset drift, and THD may be degraded compared to operation outside this region.

A double-folded cascode adds the signal from the two input pairs and presents a differential signal to the class AB output stage. Normally, input bias current is approximately 500fA. However, large inputs (greater than 300mV beyond the supply rails) can turn on the OPA350's input protection diodes, causing excessive current to flow in or out of the input pins. Momentary voltages greater than 300mV beyond the power supply can be tolerated if the current on the input pins is limited to 10mA. This is easily accomplished with an input resistor, as shown in Figure 3. Many input signals are inherently current-limited to less than 10mA; therefore, a limiting resistor is not required.

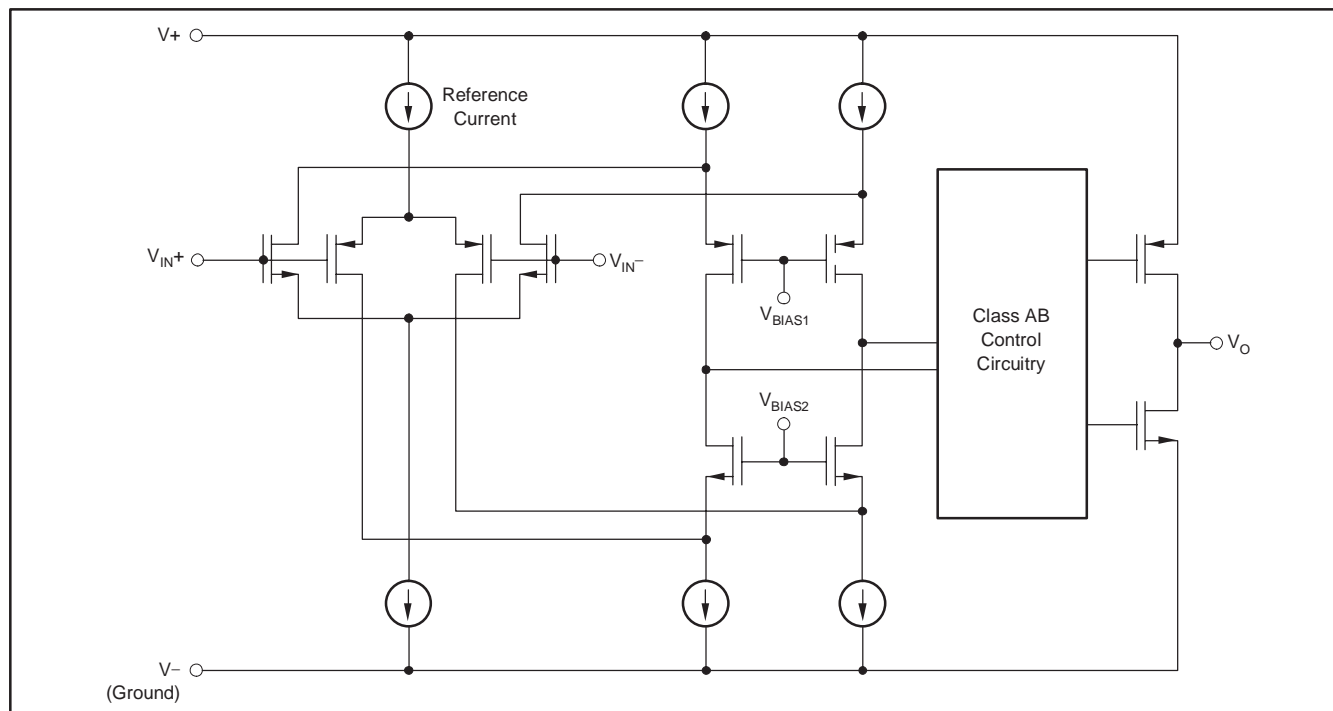


Figure 2. Simplified Schematic

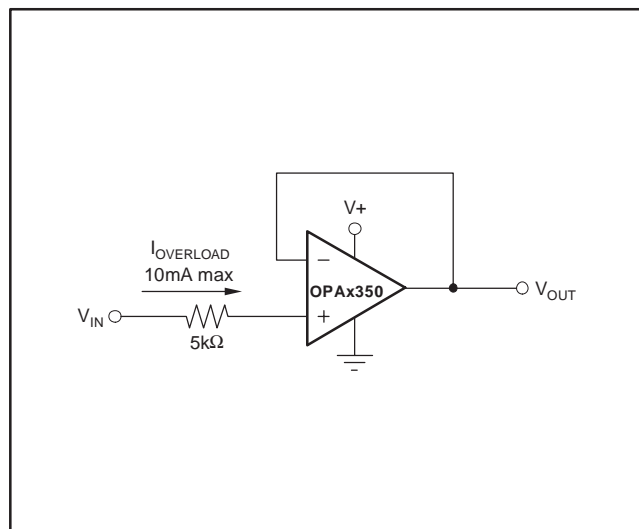


Figure 3. Input Current Protection for Voltages Exceeding the Supply Voltage

## RAIL-TO-RAIL OUTPUT

A class AB output stage with common-source transistors is used to achieve rail-to-rail output. For light resistive loads ( $>10\text{k}\Omega$ ), the output voltage swing is typically ten millivolts from the supply rails. With heavier resistive loads ( $600\Omega$  to  $10\text{k}\Omega$ ), the output can swing to

within a few tens of millivolts from the supply rails and maintain high open-loop gain. See the typical characteristics *Output Voltage Swing vs Output Current* and *Open-Loop Gain vs Output Voltage*.

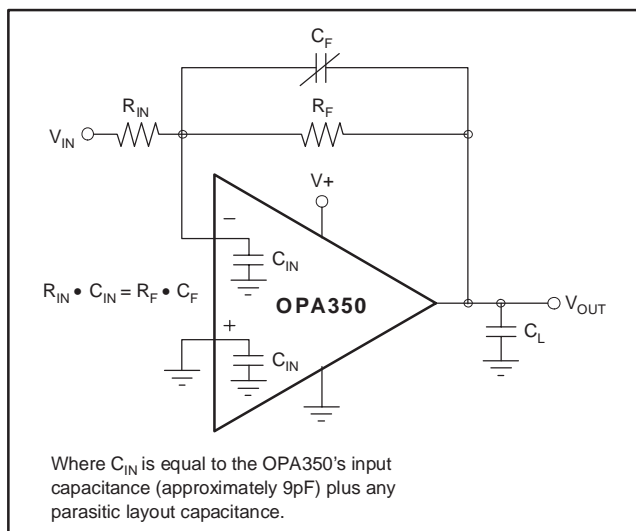
## CAPACITIVE LOAD AND STABILITY

OPA350 series op amps can drive a wide range of capacitive loads. However, all op amps under certain conditions may become unstable. Op amp configuration, gain, and load value are just a few of the factors to consider when determining stability. An op amp in unity-gain configuration is the most susceptible to the effects of capacitive load. The capacitive load reacts with the op amp's output impedance, along with any additional load resistance, to create a pole in the small-signal response that degrades the phase margin.

In unity gain, OPA350 series op amps perform well with very large capacitive loads. Increasing gain enhances the amplifier's ability to drive more capacitance. The typical characteristic *Small-Signal Overshoot vs Capacitive Load* shows performance with a  $1\text{k}\Omega$  resistive load. Increasing load resistance improves capacitive load drive capability.

## FEEDBACK CAPACITOR IMPROVES RESPONSE

For optimum settling time and stability with high-impedance feedback networks, it may be necessary to add a feedback capacitor across the feedback resistor,  $R_F$ , as shown in Figure 4. This capacitor compensates for the zero created by the feedback network impedance and the OPA350's input capacitance (and any parasitic layout capacitance). The effect becomes more significant with higher impedance networks.



**Figure 4. Feedback Capacitor Improves Dynamic Performance**

It is suggested that a variable capacitor be used for the feedback capacitor since input capacitance may vary between op amps and layout capacitance is difficult to determine. For the circuit shown in Figure 4, the value of the variable feedback capacitor should be chosen so that the input resistance times the input capacitance of the OPA350 (typically 9pF) plus the estimated parasitic layout capacitance equals the feedback capacitor times the feedback resistor:

$$R_{IN} \cdot C_{IN} = R_F \cdot C_F$$

where  $C_{IN}$  is equal to the OPA350's input capacitance (sum of differential and common-mode) plus the layout capacitance. The capacitor can be varied until optimum performance is obtained.

## DRIVING A/D CONVERTERS

OPA350 series op amps are optimized for driving medium speed (up to 500kHz) sampling A/D converters. However, they also offer excellent performance for higher speed converters. The OPA350

series provides an effective means of buffering the A/D's input capacitance and resulting charge injection while providing signal gain.

Figure 5 shows the OPA350 driving an ADS7861. The ADS7861 is a dual, 500kHz, 12-bit sampling converter in the tiny SSOP-24 package. When used with the miniature package options of the OPA350 series, the combination is ideal for space-limited applications. For further information, consult the ADS7861 data sheet (SBAS110A).

## OUTPUT IMPEDANCE

The low frequency open-loop output impedance of the OPA350's common-source output stage is approximately 1k $\Omega$ . When the op amp is connected with feedback, this value is reduced significantly by the loop gain of the op amp. For example, with 122dB of open-loop gain, the output impedance is reduced in unity-gain to less than 0.001 $\Omega$ . For each decade rise in the closed-loop gain, the loop gain is reduced by the same amount which results in a ten-fold increase in effective output impedance (see the typical characteristic, *Output Impedance vs Frequency*).

At higher frequencies, the output impedance will rise as the open-loop gain of the op amp drops. However, at these frequencies the output also becomes capacitive due to parasitic capacitance. This prevents the output impedance from becoming too high, which can cause stability problems when driving capacitive loads. As mentioned previously, the OPA350 has excellent capacitive load drive capability for an op amp with its bandwidth.

## VIDEO LINE DRIVER

Figure 6 shows a circuit for a single supply,  $G = 2$  composite video line driver. The synchronized outputs of a composite video line driver extend below ground. As shown, the input to the op amp should be ac-coupled and shifted positively to provide adequate signal swing to account for these negative signals in a single-supply configuration.

The input is terminated with a 75 $\Omega$  resistor and ac-coupled with a 47 $\mu$ F capacitor to a voltage divider that provides the dc bias point to the input. In Figure 6, this point is approximately  $(V-) + 1.7V$ . Setting the optimal bias point requires some understanding of the nature of composite video signals. For best performance, one should be careful to avoid the distortion caused by the transition region of the OPA350's complementary input stage. Refer to the discussion of rail-to-rail input.

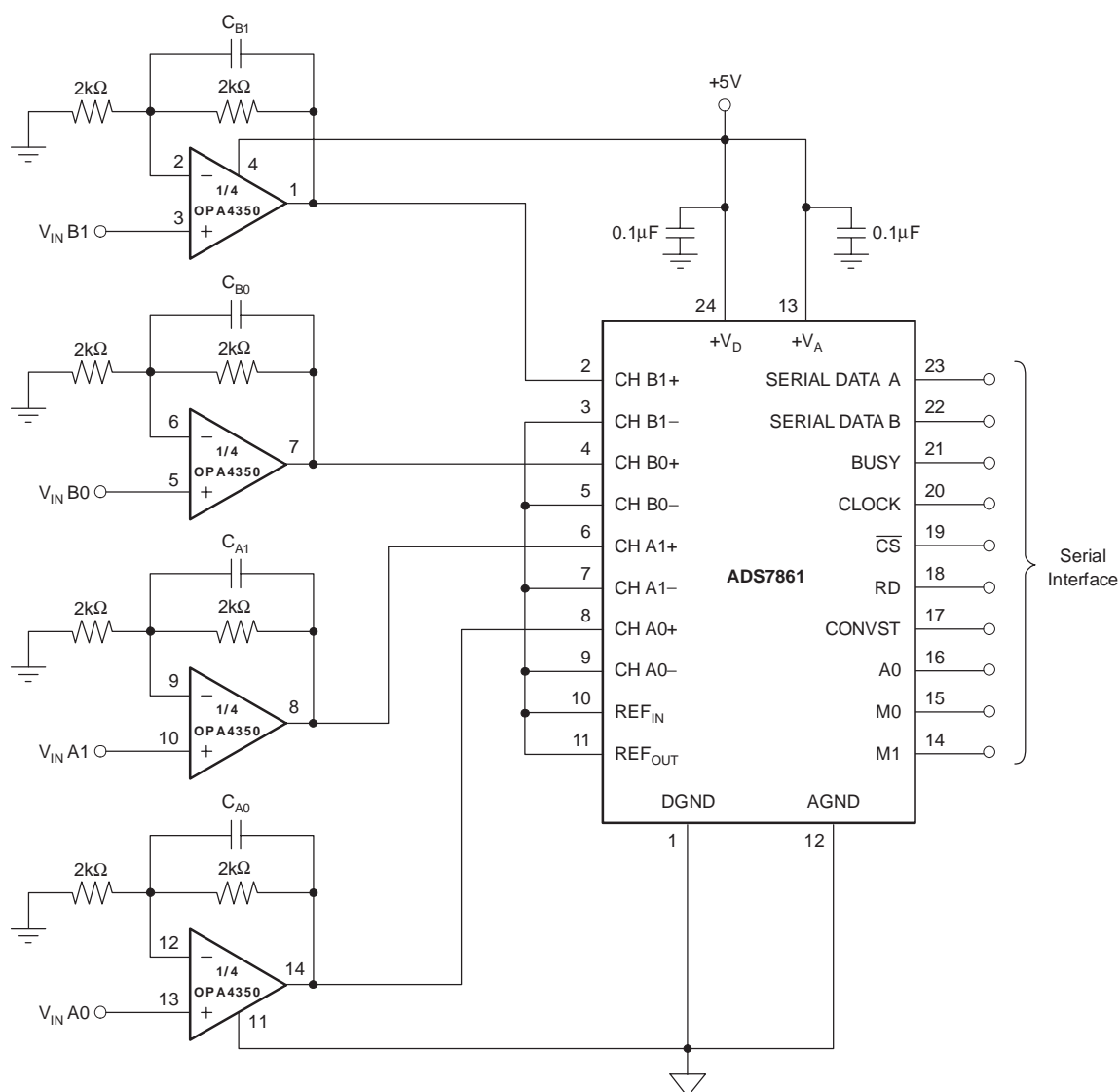
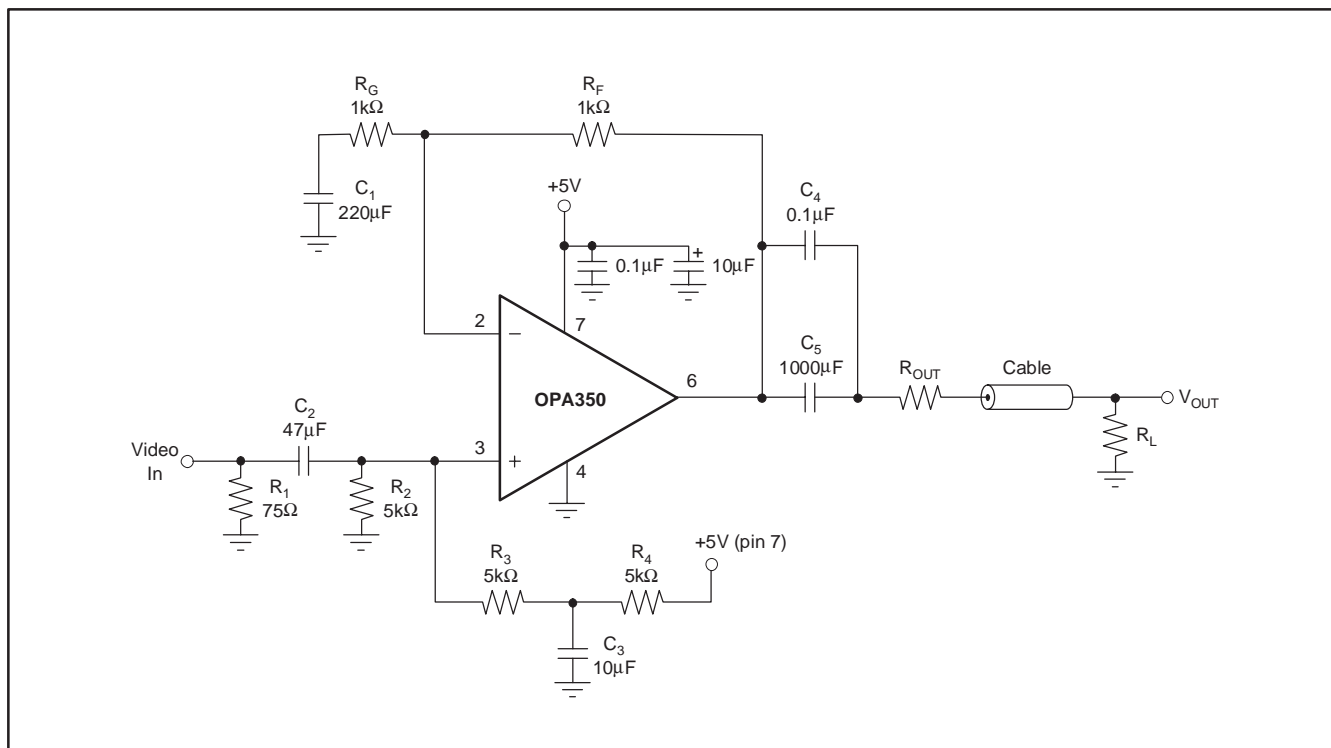
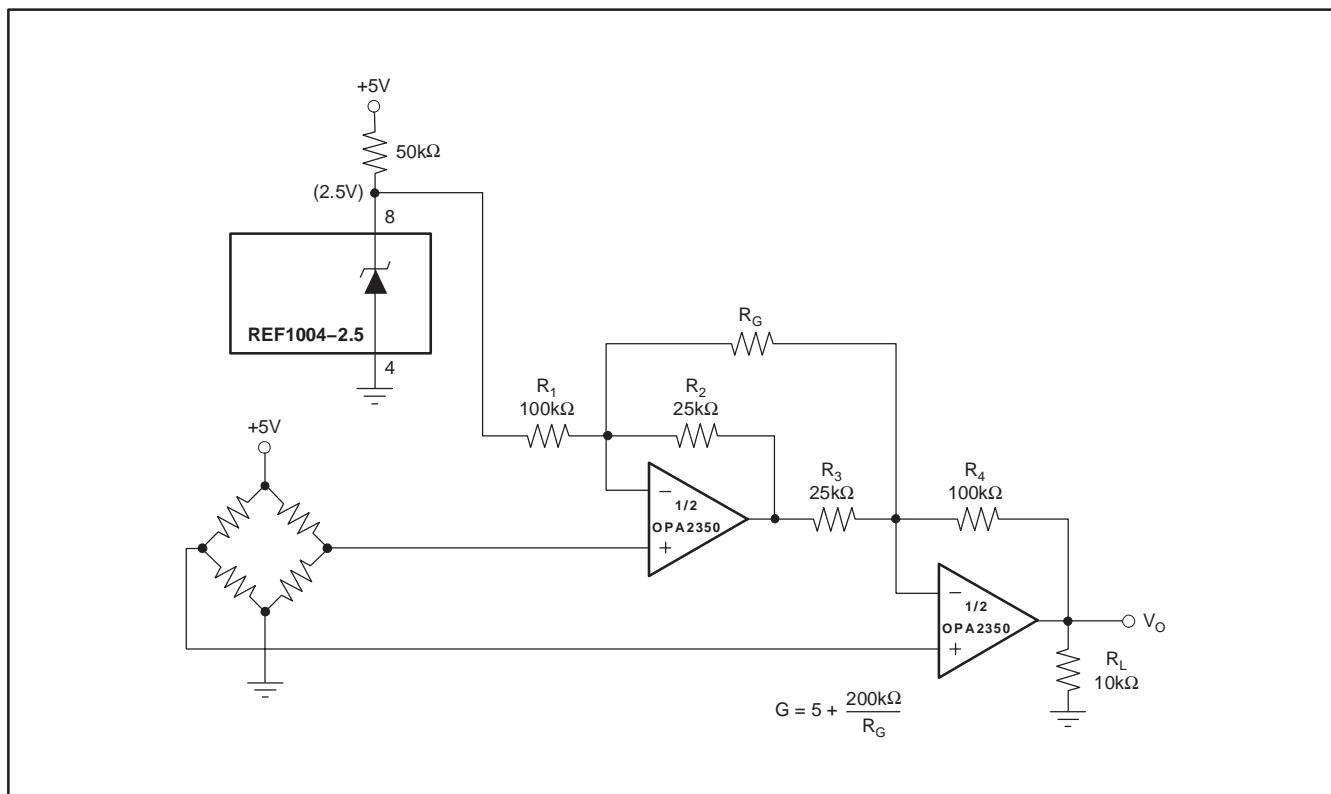


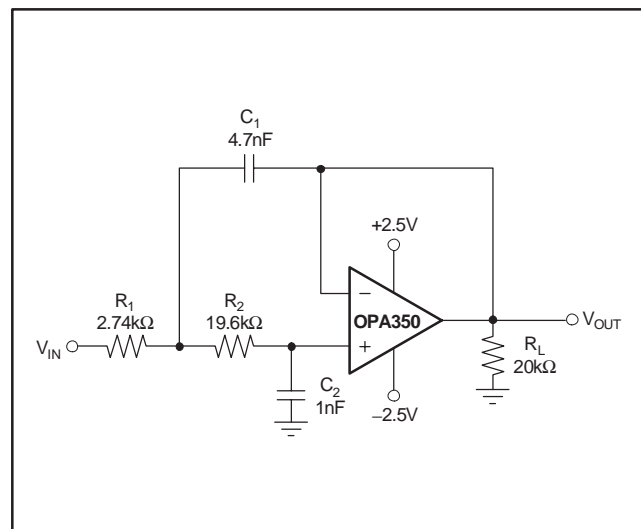
Figure 5. OPA4350 Driving Sampling A/D Converter



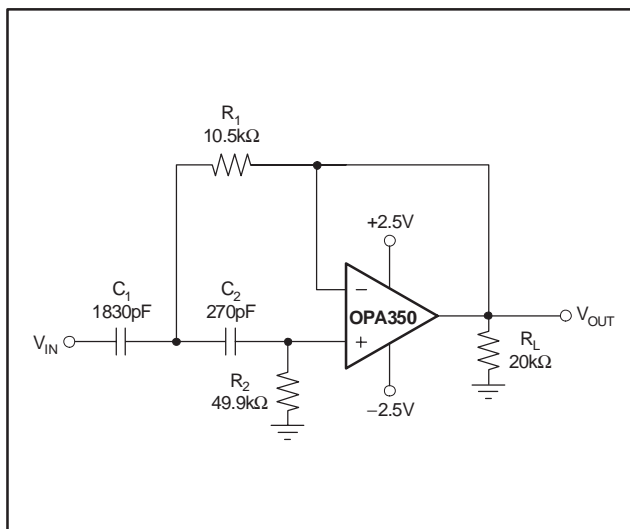
### Figure 6. Single-Supply Video Line Driver



**Figure 7. Two Op-Amp Instrumentation Amplifier With Improved High Frequency Common-Mode Rejection**



**Figure 8. 10kHz Low-Pass Filter**



**Figure 9. 10kHz High-Pass Filter**

**PACKAGING INFORMATION**

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
OPA2350EA/250	ACTIVE	VSSOP	DGK	8	250	Green (RoHS & no Sb/Br)	CU NIPDAUAG	Level-2-260C-1 YEAR	-40 to 85	D50	<a href="#">Samples</a>
OPA2350EA/250G4	ACTIVE	VSSOP	DGK	8	250	Green (RoHS & no Sb/Br)	CU NIPDAUAG	Level-2-260C-1 YEAR	-40 to 85	D50	<a href="#">Samples</a>
OPA2350EA/2K5	ACTIVE	VSSOP	DGK	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAUAG	Level-2-260C-1 YEAR	-40 to 85	D50	<a href="#">Samples</a>
OPA2350EA/2K5G4	ACTIVE	VSSOP	DGK	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAUAG	Level-2-260C-1 YEAR	-40 to 85	D50	<a href="#">Samples</a>
OPA2350PA	ACTIVE	PDIP	P	8	50	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type	-40 to 85	OPA2350PA	<a href="#">Samples</a>
OPA2350PAG4	ACTIVE	PDIP	P	8	50	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type	-40 to 85	OPA2350PA	<a href="#">Samples</a>
OPA2350UA	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 85	OPA 2350UA	<a href="#">Samples</a>
OPA2350UA/2K5	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 85	OPA 2350UA	<a href="#">Samples</a>
OPA2350UA/2K5G4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 85	OPA 2350UA	<a href="#">Samples</a>
OPA2350UAG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 85	OPA 2350UA	<a href="#">Samples</a>
OPA350EA/250	ACTIVE	VSSOP	DGK	8	250	Green (RoHS & no Sb/Br)	CU NIPDAUAG	Level-2-260C-1 YEAR	-40 to 85	C50	<a href="#">Samples</a>
OPA350EA/250G4	ACTIVE	VSSOP	DGK	8	250	Green (RoHS & no Sb/Br)	CU NIPDAUAG	Level-2-260C-1 YEAR	-40 to 85	C50	<a href="#">Samples</a>
OPA350EA/2K5	ACTIVE	VSSOP	DGK	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAUAG	Level-2-260C-1 YEAR	-40 to 85	C50	<a href="#">Samples</a>
OPA350EA/2K5G4	ACTIVE	VSSOP	DGK	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAUAG	Level-2-260C-1 YEAR	-40 to 85	C50	<a href="#">Samples</a>
OPA350PA	ACTIVE	PDIP	P	8	50	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type	-40 to 85	OPA350PA	<a href="#">Samples</a>
OPA350PAG4	ACTIVE	PDIP	P	8	50	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type	-40 to 85	OPA350PA	<a href="#">Samples</a>
OPA350UA	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 85	OPA 350UA	<a href="#">Samples</a>

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
OPA350UA/2K5	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 85	OPA 350UA	<a href="#">Samples</a>
OPA350UA/2K5G4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 85	OPA 350UA	<a href="#">Samples</a>
OPA350UAG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 85	OPA 350UA	<a href="#">Samples</a>
OPA4350EA/250	ACTIVE	SSOP	DBQ	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR		OPA 4350EA	<a href="#">Samples</a>
OPA4350EA/250G4	ACTIVE	SSOP	DBQ	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR		OPA 4350EA	<a href="#">Samples</a>
OPA4350EA/2K5	ACTIVE	SSOP	DBQ	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 85	OPA 4350EA	<a href="#">Samples</a>
OPA4350UA	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR		OPA4350UA	<a href="#">Samples</a>
OPA4350UA/2K5	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR		OPA4350UA	<a href="#">Samples</a>
OPA4350UA/2K5G4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR		OPA4350UA	<a href="#">Samples</a>
OPA4350UAG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR		OPA4350UA	<a href="#">Samples</a>

<sup>(1)</sup> The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

<sup>(2)</sup> Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)



- (3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

**Important Information and Disclaimer:** The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

**TAPE AND REEL INFORMATION**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
OPA2350EA/250	VSSOP	DGK	8	250	180.0	12.4	5.3	3.4	1.4	8.0	12.0	Q1
OPA2350EA/2K5	VSSOP	DGK	8	2500	330.0	12.4	5.3	3.4	1.4	8.0	12.0	Q1
OPA350EA/250	VSSOP	DGK	8	250	180.0	12.4	5.3	3.4	1.4	8.0	12.0	Q1
OPA350UA/2K5	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
OPA4350EA/250	SSOP	DBQ	16	250	180.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
OPA4350EA/2K5	SSOP	DBQ	16	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
OPA4350UA/2K5	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1

## TAPE AND REEL BOX DIMENSIONS



\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
OPA2350EA/250	VSSOP	DGK	8	250	210.0	185.0	35.0
OPA2350EA/2K5	VSSOP	DGK	8	2500	367.0	367.0	35.0
OPA350EA/250	VSSOP	DGK	8	250	210.0	185.0	35.0
OPA350UA/2K5	SOIC	D	8	2500	367.0	367.0	35.0
OPA4350EA/250	SSOP	DBQ	16	250	210.0	185.0	35.0
OPA4350EA/2K5	SSOP	DBQ	16	2500	367.0	367.0	35.0
OPA4350UA/2K5	SOIC	D	14	2500	367.0	367.0	38.0

P (R-PDIP-T8)

PLASTIC DUAL-IN-LINE PACKAGE



- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. Falls within JEDEC MS-001 variation BA.

DGK (S-PDSO-G8)

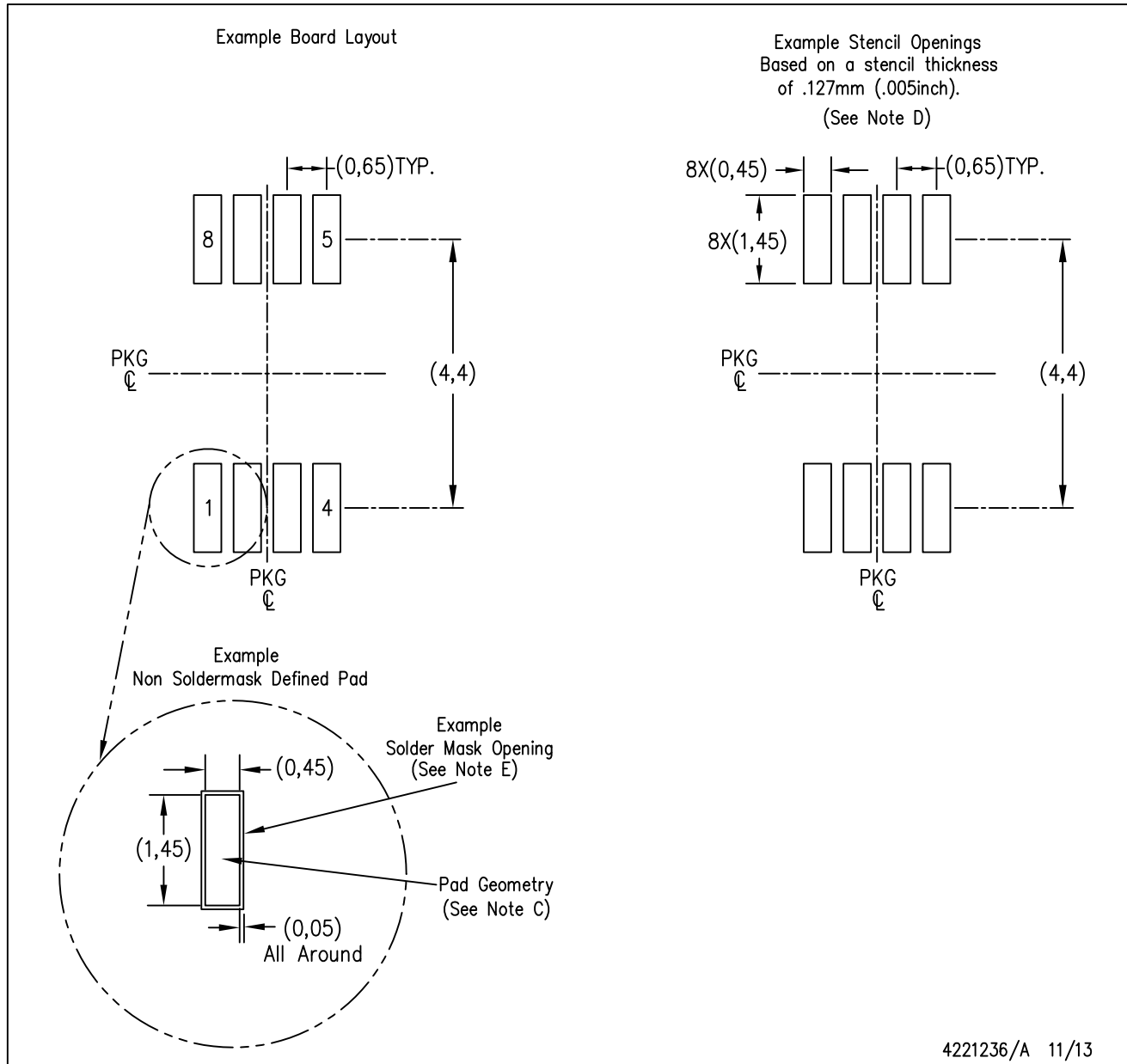
PLASTIC SMALL-OUTLINE PACKAGE



- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 per end.
  - D. Body width does not include interlead flash. Interlead flash shall not exceed 0.50 per side.
  - E. Falls within JEDEC MO-187 variation AA, except interlead flash.

DGK (S-PDSO-G8)

PLASTIC SMALL OUTLINE PACKAGE



- NOTES:
- All linear dimensions are in millimeters.
  - This drawing is subject to change without notice.
  - Publication IPC-7351 is recommended for alternate designs.
  - Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
  - Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



4040047-5/M 06/11

NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- D. Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AB.

D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Publication IPC-7351 is recommended for alternate designs.
  - D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
  - E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



D (R-PDSO-G8)

PLASTIC SMALL OUTLINE



4040047-3/M 06/11

- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - $\triangle C$  Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
  - $\triangle D$  Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
  - E. Reference JEDEC MS-012 variation AA.

D (R-PDSO-G8)

PLASTIC SMALL OUTLINE

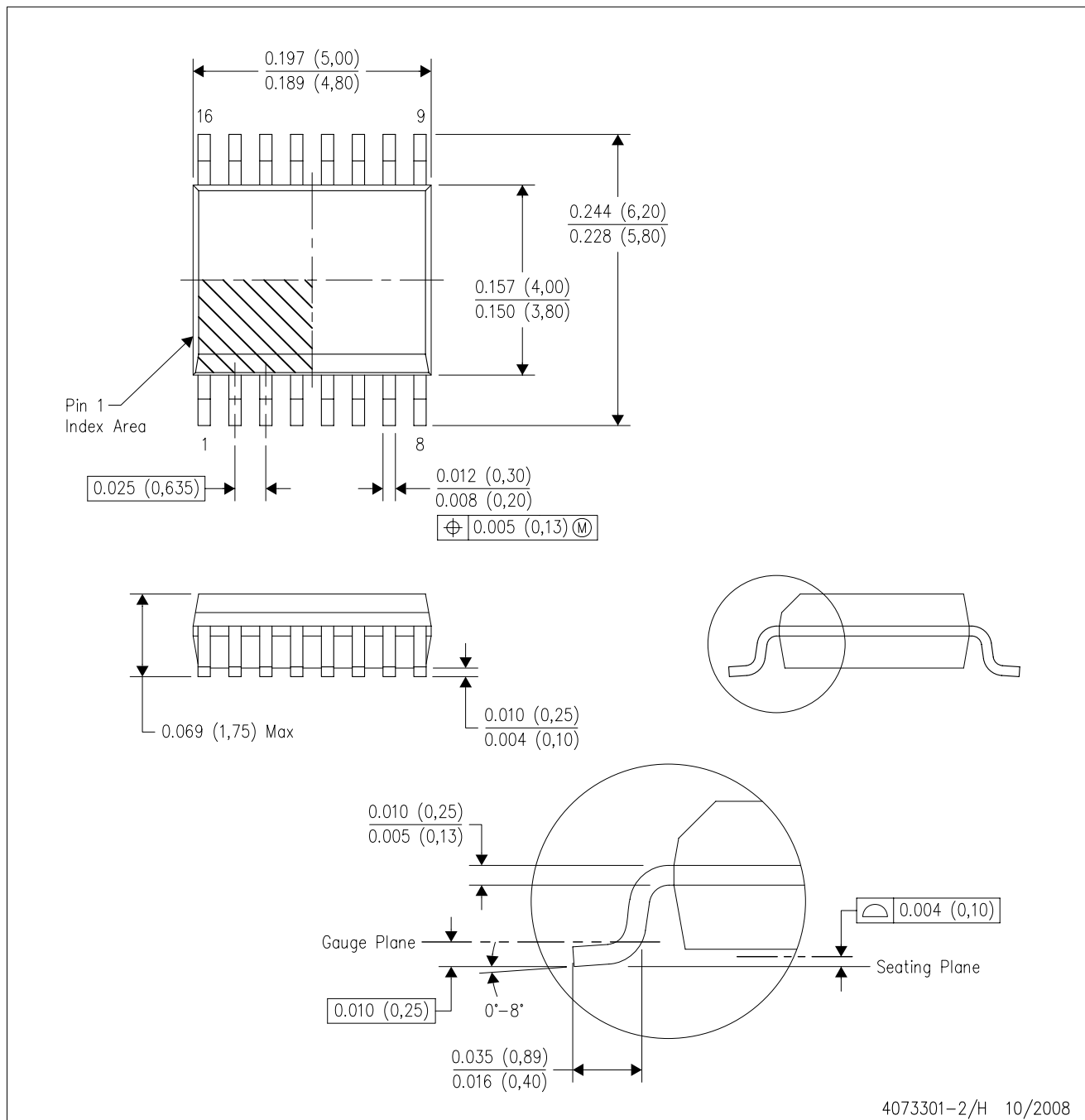


4211283-2/E 08/12

- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Publication IPC-7351 is recommended for alternate designs.
  - D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
  - E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

DBQ (R-PDSO-G16)

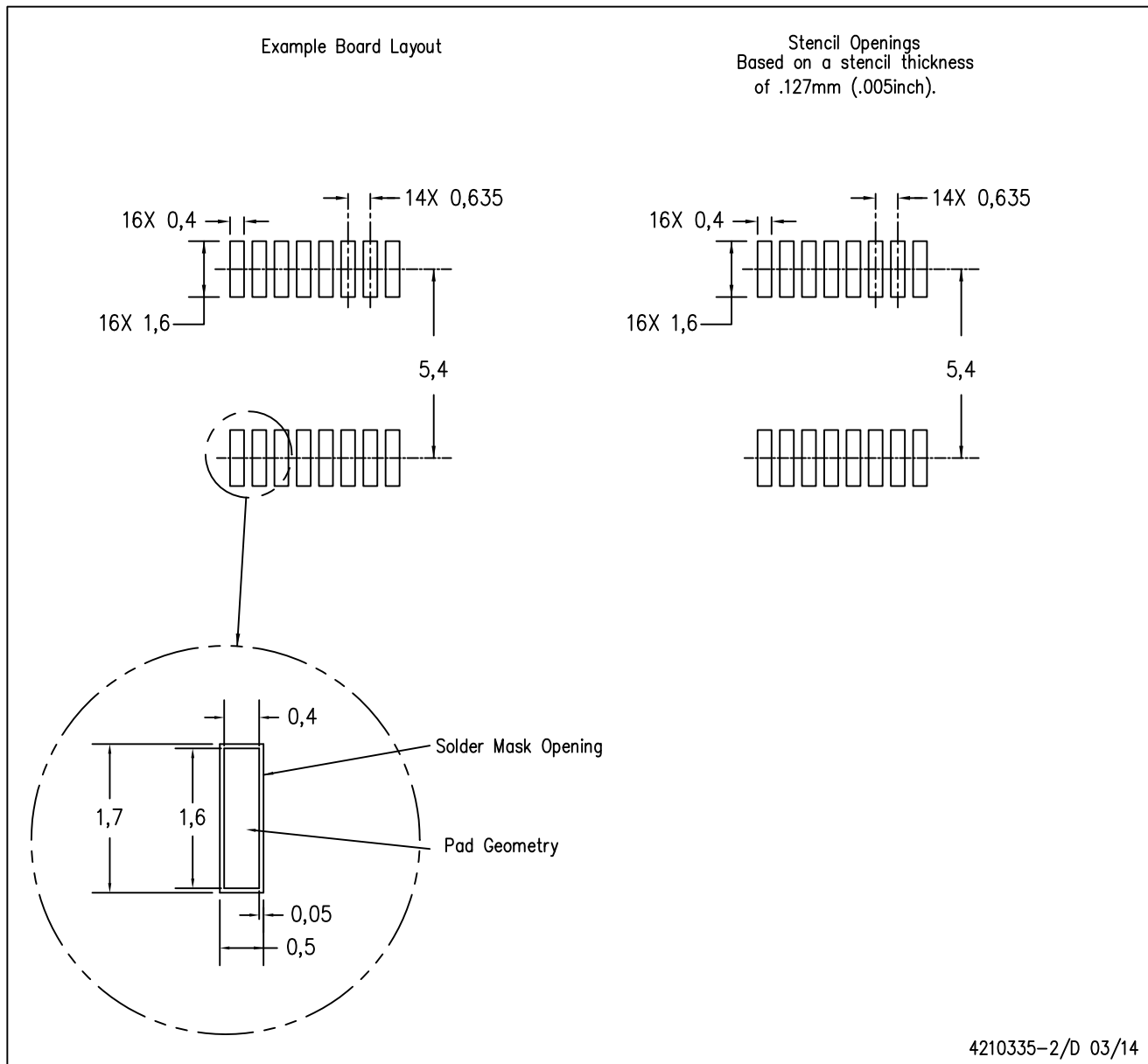
PLASTIC SMALL-OUTLINE PACKAGE



- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15) per side.
  - D. Falls within JEDEC MO-137 variation AB.

DBQ (R-PDSO-G16)

PLASTIC SMALL OUTLINE PACKAGE



- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Publication IPC-7351 is recommended for alternate designs.
  - D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Example stencil design based on a 50% volumetric metal load solder paste. Refer to IPC-7525 for other stencil recommendations.

## IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, enhancements, improvements and other changes to its semiconductor products and services per JESD46, latest issue, and to discontinue any product or service per JESD48, latest issue. Buyers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All semiconductor products (also referred to herein as "components") are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its components to the specifications applicable at the time of sale, in accordance with the warranty in TI's terms and conditions of sale of semiconductor products. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by applicable law, testing of all parameters of each component is not necessarily performed.

TI assumes no liability for applications assistance or the design of Buyers' products. Buyers are responsible for their products and applications using TI components. To minimize the risks associated with Buyers' products and applications, Buyers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any patent right, copyright, mask work right, or other intellectual property right relating to any combination, machine, or process in which TI components or services are used. Information published by TI regarding third-party products or services does not constitute a license to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of significant portions of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI components or services with statements different from or beyond the parameters stated by TI for that component or service voids all express and any implied warranties for the associated TI component or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Buyer acknowledges and agrees that it is solely responsible for compliance with all legal, regulatory and safety-related requirements concerning its products, and any use of TI components in its applications, notwithstanding any applications-related information or support that may be provided by TI. Buyer represents and agrees that it has all the necessary expertise to create and implement safeguards which anticipate dangerous consequences of failures, monitor failures and their consequences, lessen the likelihood of failures that might cause harm and take appropriate remedial actions. Buyer will fully indemnify TI and its representatives against any damages arising out of the use of any TI components in safety-critical applications.

In some cases, TI components may be promoted specifically to facilitate safety-related applications. With such components, TI's goal is to help enable customers to design and create their own end-product solutions that meet applicable functional safety standards and requirements. Nonetheless, such components are subject to these terms.

No TI components are authorized for use in FDA Class III (or similar life-critical medical equipment) unless authorized officers of the parties have executed a special agreement specifically governing such use.

Only those TI components which TI has specifically designated as military grade or "enhanced plastic" are designed and intended for use in military/aerospace applications or environments. Buyer acknowledges and agrees that any military or aerospace use of TI components which have **not** been so designated is solely at the Buyer's risk, and that Buyer is solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI has specifically designated certain components as meeting ISO/TS16949 requirements, mainly for automotive use. In any case of use of non-designated products, TI will not be responsible for any failure to meet ISO/TS16949.

### Products

Audio	<a href="http://www.ti.com/audio">www.ti.com/audio</a>
Amplifiers	<a href="http://amplifier.ti.com">amplifier.ti.com</a>
Data Converters	<a href="http://dataconverter.ti.com">dataconverter.ti.com</a>
DLP® Products	<a href="http://www.dlp.com">www.dlp.com</a>
DSP	<a href="http://dsp.ti.com">dsp.ti.com</a>
Clocks and Timers	<a href="http://www.ti.com/clocks">www.ti.com/clocks</a>
Interface	<a href="http://interface.ti.com">interface.ti.com</a>
Logic	<a href="http://logic.ti.com">logic.ti.com</a>
Power Mgmt	<a href="http://power.ti.com">power.ti.com</a>
Microcontrollers	<a href="http://microcontroller.ti.com">microcontroller.ti.com</a>
RFID	<a href="http://www.ti-rfid.com">www.ti-rfid.com</a>
OMAP Applications Processors	<a href="http://www.ti.com/omap">www.ti.com/omap</a>
Wireless Connectivity	<a href="http://www.ti.com/wirelessconnectivity">www.ti.com/wirelessconnectivity</a>

### Applications

Automotive and Transportation	<a href="http://www.ti.com/automotive">www.ti.com/automotive</a>
Communications and Telecom	<a href="http://www.ti.com/communications">www.ti.com/communications</a>
Computers and Peripherals	<a href="http://www.ti.com/computers">www.ti.com/computers</a>
Consumer Electronics	<a href="http://www.ti.com/consumer-apps">www.ti.com/consumer-apps</a>
Energy and Lighting	<a href="http://www.ti.com/energy">www.ti.com/energy</a>
Industrial	<a href="http://www.ti.com/industrial">www.ti.com/industrial</a>
Medical	<a href="http://www.ti.com/medical">www.ti.com/medical</a>
Security	<a href="http://www.ti.com/security">www.ti.com/security</a>
Space, Avionics and Defense	<a href="http://www.ti.com/space-avionics-defense">www.ti.com/space-avionics-defense</a>
Video and Imaging	<a href="http://www.ti.com/video">www.ti.com/video</a>

### TI E2E Community

[e2e.ti.com](http://e2e.ti.com)